



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#H2gw  
09/30/03 ✓

Application Serial No. 09/148,723  
Filing Date September 3, 1998  
Inventor Warren M. Farnworth et al.  
Assignee Micron Technology, Inc.  
Group Art Unit 3729  
Examiner D. Tugbang  
Attorney's Docket No. MI22-981  
Title: Methods of Bonding Solder Balls To Bond Pads on a Substrate

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

References- - See attached Form PTO-1449

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the reference listed on the attached Form PTO-1449. No admission is made regarding whether the submitted reference is prior art.


This Supplemental Information Disclosure Statement is being filed before the mailing date of further examination after an RCE application filed on April 29, 2003. Therefore, no fee is believed to be required. However, in the event that a fee is required for filing this Supplemental Information Disclosure Statement, please charge the fee specified under 37 C.F.R. § 1.17(p) to Deposit Account No. 23-0925.

Citation of this reference is respectfully requested.

Adjustment date: 10/07/2003 SDIRETA1  
09/24/2003 JBA/ANAN 00000125 230925 09148723  
01 FC:1806 180.00 CR

Respectfully submitted,

Date: 6-18-03

  
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